

KAI-0340 Imager Board User's Manual



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Description

The KAI-0340 Imager Evaluation Board, referred to in this document as the Imager Board, is designed to be used as part of a two-board set, used in conjunction with a Timing Generator Board. ON Semiconductor offers an Imager Board / Timing Generator Board package that has been designed and configured to operate with the KAI-0340 Image Sensor.

The Timing Generator Board generates the timing signals necessary to operate the CCD, and provides the power required by the Imager Board. The timing signals, in LVDS format, and the power, are provided to the Imager Board via the interface connector (J1). In addition, the Timing Generator Board performs the processing and digitization of the analog video output of the Imager Board.

The KAI-0340 Imager Board has been designed to operate the KAI-0340 with the specified performance at 40 MHz pixel clocking rate and nominal operating conditions. (See the KAI-0340 Performance Specifications for details).

Eval Board User's Manual

For testing and characterization purposes, the KAI-0340 Imager board provides the ability to adjust many of the CCD bias voltages and CCD clock level voltages by adjusting potentiometers on the board. The Imager Board provides the means to modify other device operating parameters (e.g., CCD reset clock pulse width) by populating components differently on the board.

Some circuitry on the Imager Board (e.g., remote DAC control of bias and clock level voltages) is intended for ON Semiconductor test purposes only, and may not be populated.

Imager Board Input Requirements

Table 1. POWER REQUIREMENTS

| Power Supplies | Minimum | Typical | Maximum | Units |
|-----------------|---------|---------|---------|-------|
| +5 V_MTR Supply | 4.9 | 5 | 5.1 | V |
| | | 800 | | mA |
| -5 V_MTR Supply | -5.1 | -5 | -4.9 | V |
| | | 200 | | mA |
| VPLUS Supply | 18 | 20 | 21 | V |
| | | 250 | | mA |
| VMINUS Supply | -21 | -20 | -18 | V |
| | | 250 | | mA |

Table 2. SIGNAL LEVEL REQUIREMENTS

| Input Signals (LVDS) | V _{min} | V _{threshold} | V _{max} | Units | Signal | Comments |
|----------------------|------------------|------------------------|------------------|-------|------------|-------------------------|
| IMAGER_IN0 | 0 | ±0.1 | 2.4 | V | AMP ENABLE | Output Amplifier Enable |
| IMAGER_IN1 | 0 | ±0.1 | 2.4 | V | H1A | H1A clock |
| IMAGER_IN2 | 0 | ±0.1 | 2.4 | V | H1B | H1B clock |
| IMAGER_IN3 | 0 | ±0.1 | 2.4 | V | H2A | H2A clock |
| IMAGER_IN4 | 0 | ±0.1 | 2.4 | V | H2B | H2B clock |
| IMAGER_IN5 | 0 | ±0.1 | 2.4 | V | RESET | Reset clock |
| IMAGER_IN6 | 0 | ±0.1 | 2.4 | V | V1 | V1 clock |

Table 2. SIGNAL LEVEL REQUIREMENTS

| Input Signals (LVDS) | V _{min} | V _{threshold} | V _{max} | Units | Signal | Comments |
|----------------------|------------------|------------------------|------------------|-------|-------------|--------------------------------|
| IMAGER_IN7 | 0 | ±0.1 | 2.4 | V | V2 | V2 clock |
| IMAGER_IN8 | 0 | ±0.1 | 2.4 | V | VCLK_ENABLE | Outer V2 clock control |
| IMAGER_IN9 | 0 | ±0.1 | 2.4 | V | V3RD | V2 Clock 3 rd level |
| IMAGER_IN10 | 0 | ±0.1 | 2.4 | V | FDG | Outer Fast Dump clock |
| IMAGER_IN11 | 0 | ±0.1 | 2.4 | V | VES | Electronic Shutter clock |
| IMAGER_IN12 | 0 | ±0.1 | 2.4 | V | VIDEO_MUX | VOUT_MUX (J2) control |
| IMAGER_IN13 | 0 | ±0.1 | 2.4 | V | FDG_CENTER | Center Fast Dump clock |
| IMAGER_IN14 | 0 | ±0.1 | 2.4 | V | | (not used) |
| IMAGER_IN15 | 0 | ±0.1 | 2.4 | V | | (not used) |

KAI-0340 IMAGER BOARD ARCHITECTURE OVERVIEW

The following sections describe the functional blocks of the KAI-0340 Imager Board (Refer to Figure 1).

Power Filtering and Regulation

Power is supplied to the Imager Board via the J1 interface connector. The power supplies are de-coupled and filtered with ferrite beads and capacitors to suppress noise. Voltage regulators are used to create the +15 V and -15 V supplies from the VPLUS and VMINUS supplies.

LVDS Receivers / TTL Buffers

LVDS timing signals are input to the Imager Board via the J1 interface connector. These signals are shifted to TTL levels before being sent to the CCD clock drivers.

Reset Clock One-Shot

The pulse width of the RESET_CCD clock is set by a programmable One-Shot. The One-Shot can be configured to provide a RESET_CCD clock signal with a pulse width from 5 ns to 15 ns. If pulse width control functionality is provided by the Timing Board, the One-Shot may be removed and bypassed by installing R170.

CCD Pixel-Rate Clock Drivers (H1, H2 & Reset Clocks)

The pixel rate CCD clock drivers utilize two fast switching transistors that are designed to translate TTL-level input clock signals to the voltage levels required by the CCD. The high level and low level of the CCD clocks are set by potentiometers, and are buffered by operational amplifiers configured as voltage followers.

CCD VCLK Drivers

The vertical clock (VCLK) drivers consist of MOSFET driver IC's. These drivers are designed to translate the TTL-level clock signals to the voltage levels required by the CCD. The high, middle, and low voltage levels of the vertical clocks are set by potentiometers buffered by operational amplifiers. The VHIGH and VLOW op-amps have a gain of 1.25, to allow the magnitude of the voltages to be adjusted to 12.5 V when using DAC control.

The current sources for these voltage levels are high current (up to 600 mA) transistors. The V2_CCD high level clock voltage is switched from V_MID to V_HIGH once per frame to transfer the charge from the photodiodes to the vertical CCDs.

The V1 clock driver is a 2-level driver circuit, switching between VMID and VLOW voltage levels. There are two 3-level clock driver circuits, V2 and V2C, which are identical except for the input logic, which is controlled by the VCLK_ENABLE signal. This signal is used to control the outer V2 clocks to implement certain imaging modes where only the center rows are read out.

CCD FDG Driver

The Fast Dump clock drivers consist of a transistor that will switch the voltage on the FD and FDC pins of the CCD from FDG_LOW to FDG_HIGH during Fast Dump Gate operations. When not in operation, or when the Fast Dump Gate feature is not being utilized, the FDG pin of the CCD is held at FDG_LOW. The FDG_HIGH and FDG_LOW voltage levels of the FDG driver are set by potentiometers, buffered by operational amplifiers configured as voltage followers.

The FD and FDC CCD inputs are clocked separately, to implement certain imaging modes where only the center columns are read out.

VSUB/VES Circuit

The quiescent CCD substrate voltage (VSUB) is set by a potentiometer and resistor divider network. The VSUB voltage is buffered by an operational amplifier configured with a gain of 1.40, to allow the voltage to be adjusted to nearly 14.0 V.

For electronic shutter operation, the VES signal drives a transistor amplifier circuit which AC-couples the voltage difference between the VPLUS and VMINUS supplies onto the Substrate voltage. This creates the necessary potential to clear all charge from the photodiodes, thereby acting as an electronic shutter to control exposure.

VDD Bias Voltages

The VDDL and VDDR video output amplifier supplies in the CCD are coupled directly to the +15 V regulated supply on the Imager Board. The Imager Board contains optional circuitry which allows this voltage to be adjusted through the Alternate VDD bias circuit. This circuitry is for ON Semiconductor use only, and is not enabled.

The Imager Board contains optional circuitry to control a multiplexer which switches the VDD voltage from +15 V to ALT_VDD. This circuitry is for ON Semiconductor use only, and is not enabled.

ESD Bias Voltage

The RESET and HCLK gates on the KAI-0340 CCD are protected from ESD damage by internal circuitry. The ESD bias voltage is set by a potentiometer, buffered by an operational amplifier configured as a voltage follower. The ESD bias voltage must be more negative than any of the protected gates during operation and powerup. In order to ensure these conditions are met, diodes are connected external to the CCD between the protected gates and VESD, and between VSUB and VESD.

It is also recommended that during powerup of the Timing Board and Imager Board, the VMINUS supply is applied before, or simultaneously with, the other power supplies. For more information, refer to the KAI-0340 CCD Image Sensor Device Performance Specification.

CCD Image Sensor

This evaluation board supports the KAI-0340 Interline Image Sensor.

Emitter-Followers

The VOUT_LEFT_CCD and VOUT_RIGHT_CCD video output signals are buffered using bipolar junction transistors in the emitter-follower configuration. These circuits also provide the necessary 5 mA current sink for the CCD output circuits. The voltage gain of this stage is approximately 0.96.

Line Drivers

The buffered VOUT_LEFT_CCD and VOUT_RIGHT_CCD signals are AC-coupled and driven from the Imager Board by operational amplifiers in a non-inverting configuration. The operational amplifiers are configured to have a gain of 1.25, which yields an overall gain of 0.6 when driving the properly terminated 75 Ω video coaxial cabling from the SMB connector. This is done to prevent overloading the AFE on the Timing Board.

The video output of either channel may be multiplexed to the VOUT_MUX output. The multiplexer is controlled by the VIDEO_MUX signal. This circuitry is for Truesense Imaging use only, and is not enabled.

KAI-0340 OPERATIONAL SETTINGS

The Imager board is configured to operate the KAI-0340 Image Sensor under the following operating conditions:

Bias Voltages

The following voltages are fixed, or adjusted with a potentiometer as noted. The nominal values listed in Table 3

were correct at the time of this document’s publication, but may be subject to change; refer to the KAI-0340 device specification.

Table 3. BIAS VOLTAGES

| Description | Symbol | Min | Nom | Max | Units | Potentiometer | Notes |
|-------------------------------|--------|------|------|-------|-------|---------------|-------|
| Left Output Amplifier Supply | VDDL | | 15.0 | | V | | |
| Right Output Amplifier Supply | VDDR | | 15.0 | | V | | |
| ESD Protection | ESD | -6.0 | -9.0 | -11.0 | V | R11 | 1 |
| Substrate | VSUB | 8.5 | TBD | 14.0 | V | R17 | 1, 2 |
| Ground | GND | | 0 | | | | |

1. The Min and Max voltages in the table indicate the imager board potentiometer adjustable voltage range. These values may exceed the specified CCD operating conditions. See the KAI-0340 device specification for details.
2. The recommended VSUB voltage is specified for each CCD image sensor, and is labeled on the container as VAB.

Clock Voltages

The following clock voltage levels are fixed, or adjusted with a potentiometer as noted. The nominal values listed in

Table 4 were correct at the time of this document's publication, but may be subject to change; refer to the KAI-0340 device specification.

Table 4. CLOCK VOLTAGES

| Description | Symbol | Level | Min | Nom | Max | Units | Potentiometer | Notes |
|----------------------|-----------|-------|-------|------|------|-------|---------------|-------|
| Horizontal CCD Clock | Hxx_CCD | Low | -8.0 | -5.0 | -1.0 | V | R126 | 3, 8 |
| | | High | -5.0 | 0.0 | 5.0 | V | R92 | 4, 8 |
| Vertical CCD Clock | Vx_CCD | Low | -12.0 | -9.0 | -6.0 | V | R52 | 5, 8 |
| | | Mid | -3.0 | 0.0 | 3.0 | V | R81 | 6, 8 |
| | V2x_CCD | High | 6.0 | 10.0 | 12.0 | V | R71 | 8 |
| Reset Clock | RESET_CCD | Low | -8.0 | -3.0 | -1.0 | V | R153 | 8 |
| | | High | 0.5 | 2.0 | 5.0 | V | R135 | 8 |
| Fast Dump Clock | Fdx_CCD | Low | -11.5 | -9.0 | -5.0 | V | R62 | 7, 8 |
| VDD | +15 V | High | 2.5 | 5.0 | 7.5 | V | R45 | 8 |
| | | High | | 15.0 | | V | Fixed | |

3. The H1A_CCD, H1B_CCD, H2A_CCD, and H2B_CCD low levels are controlled by the same potentiometer (R126).
4. The H1A_CCD, H1B_CCD, H2A_CCD, and H2B_CCD high levels are controlled by the same potentiometer (R92).
5. V1_CCD and V2_CCD low levels are controlled by the same potentiometer (R52).
6. V1_CCD and V2_CCD mid levels are controlled by the same potentiometer (R81).
7. FD is used to flush the outer columns when only the center columns are read out.
8. The Min and Max voltages in the table indicate the imager board potentiometer adjustable voltage range. These values may exceed the specified CCD operating conditions. See the KAI-0340 device specification for details.

Reset Clock Pulse Width

The pulse width of RESET_CCD is set by configuring P[2..0], the inputs to the programmable one-shot U14. P[2..0] can be tied high or low to achieve the desired pulse width by populating the resistors R161-164 accordingly.

This feature is optional, as the pulsewidth may also be controlled from the Timing Board. In that case, U14 should be removed, and R170 should be installed to bypass this circuitry.

Table 5. RESET CLOCK PULSE WIDTH

| Pulse Width | P0 | P1 | P2 | R161 | R162 | R163 | R164 | Notes |
|-------------|----|----|----|------|------|------|------|-----------------|
| 15 ns | 0 | 0 | 0 | IN | IN | OUT | OUT | |
| 5 ns | 1 | 0 | 0 | IN | OUT | IN | OUT | Default Setting |
| 7.5 ns | 0 | 1 | 0 | OUT | IN | OUT | IN | |
| 10 ns | 1 | 1 | 0 | OUT | OUT | IN | IN | |

BLOCK DIAGRAM AND PERFORMANCE DATA

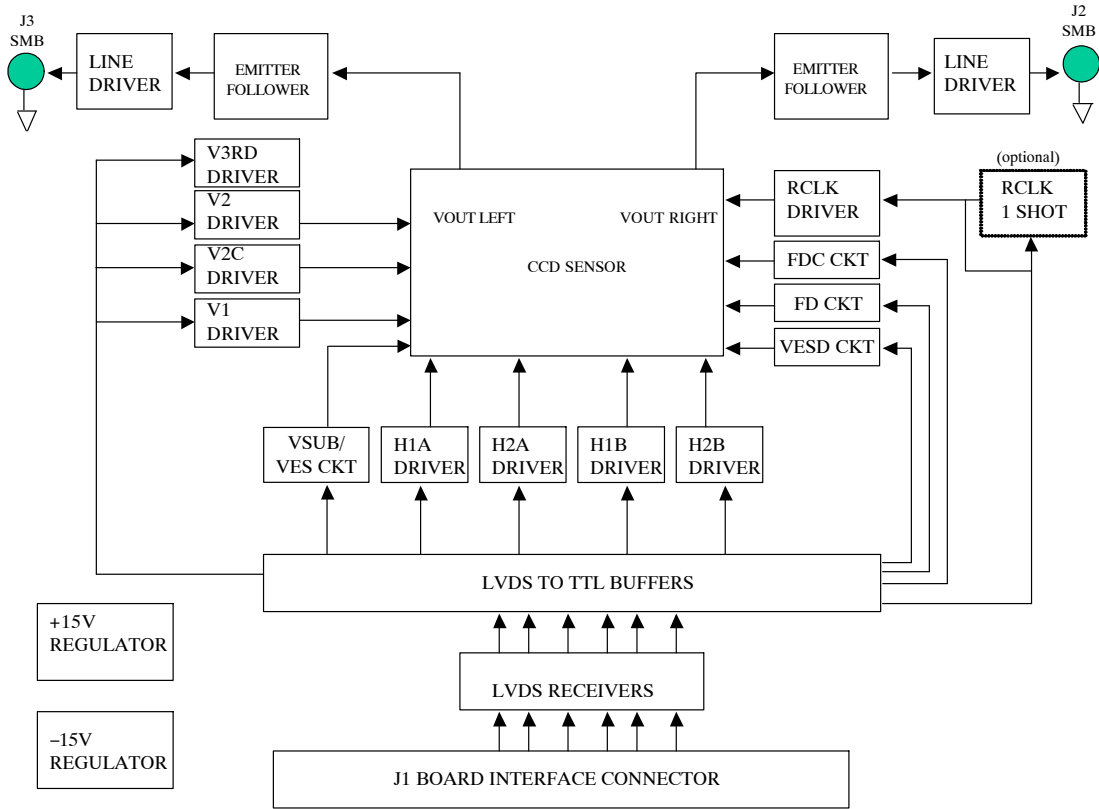


Figure 1. KAI-0340 Imager Board Block Diagram

Photon Transfer

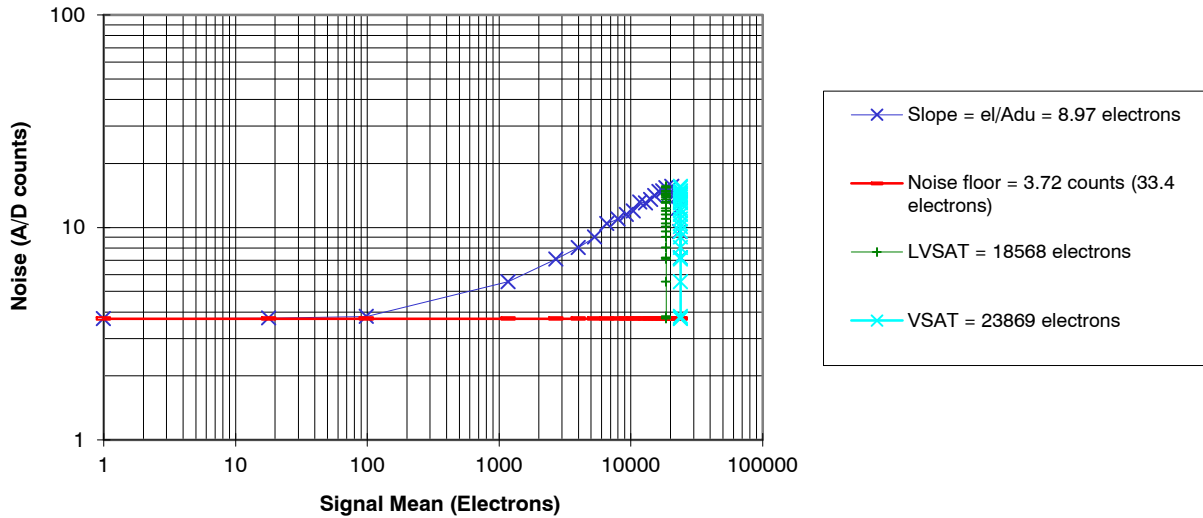


Figure 2. Measured Performance – Dynamic Range and Noise Floor

CONNECTOR ASSIGNMENTS AND PINOUTS

SMB Connectors J3 and J4

The emitter-follower buffered VOUT_LEFT and VOUT_RIGHT signals are driven from the Imager Board via the SMB connectors J4 and J3, respectively. VOUT_LEFT is the primary output from KAI-0340; VOUT_RIGHT is only used when the CCD is clocked in

dual-channel mode. Coaxial cable with a characteristic impedance of 75 Ω should be used to connect the imager board to the Timing Generator Board to match the series and terminating resistors used on these boards.

Table 6. J1 INTERFACE CONNECTOR PIN ASSIGNMENTS

| Pin | Signal | Pin | Signal |
|-----|--------------|-----|--------------|
| 1 | N.C. | 2 | N.C. |
| 3 | AGND | 4 | AGND |
| 5 | IMAGER_IN11+ | 6 | IMAGER_IN11- |
| 7 | AGND | 8 | AGND |
| 9 | IMAGER_IN10+ | 10 | IMAGER_IN10- |
| 11 | AGND | 12 | AGND |
| 13 | IMAGER_IN9+ | 14 | IMAGER_IN9- |
| 15 | AGND | 16 | AGND |
| 17 | IMAGER_IN8+ | 18 | IMAGER_IN8- |
| 19 | AGND | 20 | AGND |
| 21 | IMAGER_IN7+ | 22 | IMAGER_IN7- |
| 23 | AGND | 24 | AGND |
| 25 | IMAGER_IN6+ | 26 | IMAGER_IN6- |
| 27 | AGND | 28 | AGND |
| 29 | IMAGER_IN5+ | 30 | IMAGER_IN5- |
| 31 | AGND | 32 | AGND |
| 33 | IMAGER_IN4+ | 34 | IMAGER_IN4- |
| 35 | AGND | 36 | AGND |
| 37 | IMAGER_IN3+ | 38 | IMAGER_IN3- |
| 39 | AGND | 40 | AGND |
| 41 | IMAGER_IN2+ | 42 | IMAGER_IN2- |
| 43 | AGND | 44 | AGND |
| 45 | IMAGER_IN1+ | 46 | IMAGER_IN1- |
| 47 | N.C. | 48 | N.C. |
| 49 | AGND | 50 | AGND |
| 51 | N.C. | 52 | N.C. |
| 53 | VMINUS_MTR | 54 | VMINUS_MTR |
| 55 | N.C. | 56 | N.C. |
| 57 | AGND | 58 | AGND |
| 59 | IMAGER_IN0+ | 60 | IMAGER_IN0- |
| 61 | -5 V_MTR | 62 | -5 V_MTR |
| 63 | IMAGER_IN15+ | 64 | IMAGER_IN15- |
| 65 | AGND | 66 | AGND |
| 67 | IMAGER_IN14+ | 68 | IMAGER_IN14- |
| 69 | +5 V_MTR | 70 | +5 V_MTR |
| 71 | IMAGER_IN13+ | 72 | IMAGER_IN13- |
| 73 | AGND | 74 | AGND |
| 75 | IMAGER_IN12+ | 76 | IMAGER_IN12- |
| 77 | VPLUS_MTR | 78 | VPLUS_MTR |
| 79 | N.C. | 80 | N.C. |

Warnings and Advisories

ON Semiconductor is not responsible for customer damage to the Imager Board or Imager Board electronics. The customer assumes responsibility and care must be taken when probing, modifying, or integrating the ON Semiconductor Evaluation Board Kits.

When programming the Timing Board, the Imager Board must be disconnected from the Timing Board before power is applied. If the Imager Board is connected to the Timing Board during the reprogramming of the Altera PLD, damage to the Imager Board will occur.

Purchasers of an Evaluation Board Kit may, at their discretion, make changes to the Timing Generator Board firmware. ON Semiconductor can only support firmware developed by, and supplied by, ON Semiconductor. Changes to the firmware are at the risk of the customer.

Ordering Information

Please address all inquiries and purchase orders to:

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